

## +5V To $\pm 10V$ Voltage Converter

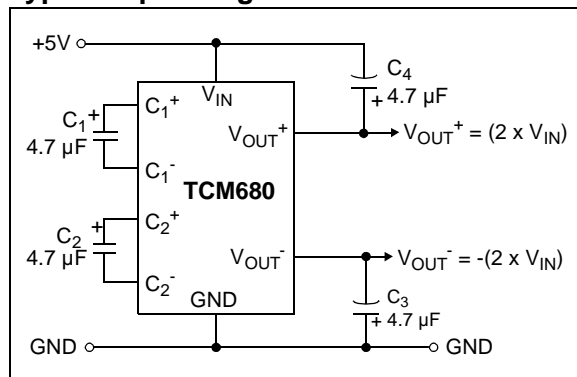
### Features

- 99% Voltage Conversion Efficiency
- 85% Power Conversion Efficiency
- Input Voltage Range:
  - +2.0V to +5.5V
- Only 4 External Capacitors Required
- 8-Pin SOIC Package

### Applications

- $\pm 10V$  From +5V Logic Supply
- $\pm 6V$  From a 3V Lithium Cell
- Handheld Instruments
- Portable Cellular Phones
- LCD Display Bias Generator
- Panel Meters
- Operational Amplifier Power Supplies

### Typical Operating Circuit



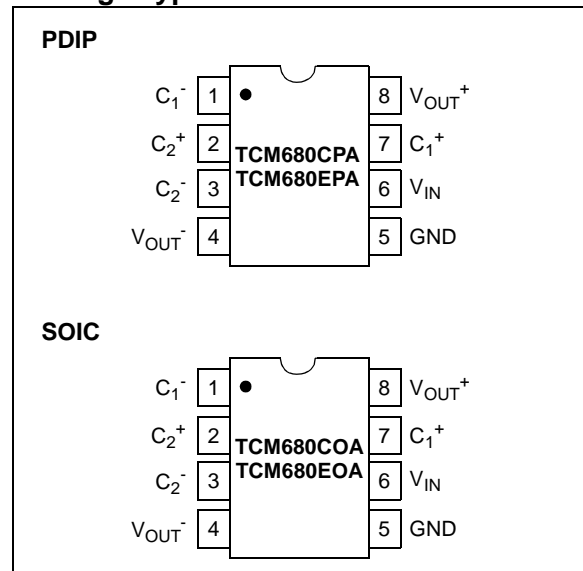
### General Description

The TCM680 is a dual charge pump, voltage converter that produces output voltages of  $+2V_{IN}$  and  $-2V_{IN}$  from a single input voltage of +2.0V to +5.5V. Common applications include  $\pm 10V$  from a single +5V logic supply and  $\pm 6V$  from a +3V lithium battery.

The TCM680 is packaged in 8-pin SOIC and PDIP packages and requires only four inexpensive, external capacitors. The charge pumps are clocked by an on-board 8 kHz oscillator. Low output source impedances (typically  $140 \Omega$ ) provide maximum output currents of 10 mA for each output. Typical power conversion efficiency is 85%.

High efficiency, small size and low cost make the TCM680 suitable for a wide variety of applications that need both positive and negative power supplies derived from a single input voltage.

### Package Type



# TCM680

## 1.0 ELECTRICAL CHARACTERISTICS

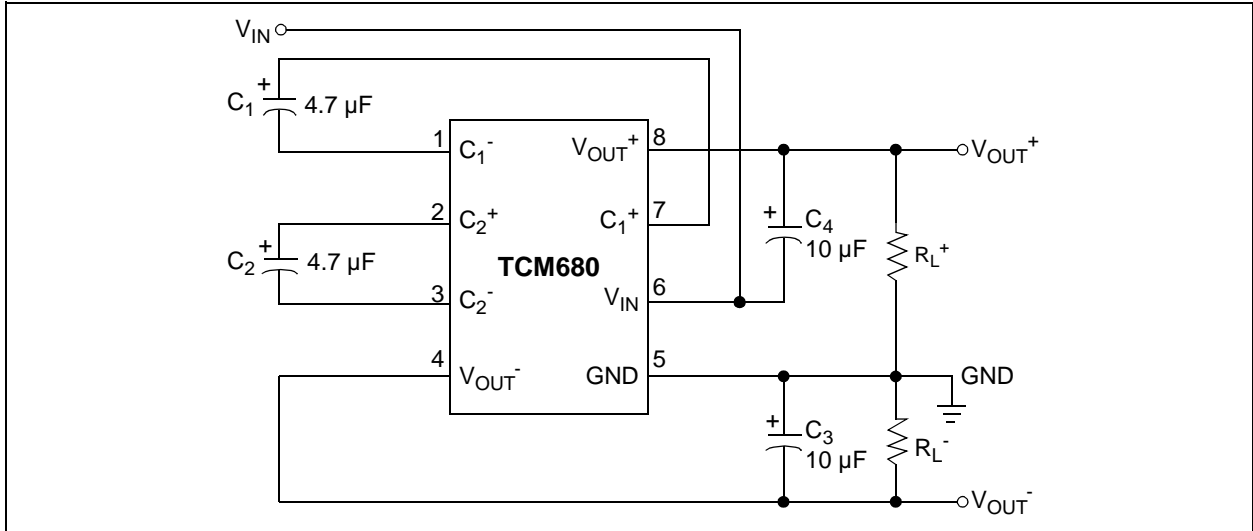
### Absolute Maximum Ratings†

$V_{IN}$ .....	+5.8V
$V_{OUT}^+$ .....	+11.6V
$V_{OUT}^-$ .....	-11.6V
$V_{OUT}^+$ Short-Circuit Duration.....	Continuous
$V_{OUT}^+$ Current .....	75 mA
$V_{IN}$ dV/dT .....	1 V/ $\mu$ sec
Power Dissipation ( $T_A \leq 70^\circ\text{C}$ )	
8-Pin PDIP .....	730 mW
8-Pin SOIC .....	470 mW
Operating Temperature Range.....	-40°C to +85°C
Storage Temperature Range .....	-65°C to +150°C
Maximum Junction Temperature .....	+150°C

† **Notice:** Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability

### DC CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, $V_{IN} = +5\text{V}$ , $T_A = +25^\circ\text{C}$ , refer to Figure 1-1.						
Parameters	Sym	Min	Typ	Max	Units	Conditions
Supply Voltage Range	$V_{IN}$	2.0	—	5.5	V	$-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$ , $R_L = 2\text{ k}\Omega$
Supply Current	$I_{IN}$	—	0.5	1.0	mA	$V_{IN} = 3\text{V}$ , $R_L = \infty$
		—	1.0	2.0		$V_{IN} = 5\text{V}$ , $R_L = \infty$
		—	—	2.5		$V_{IN} = 5\text{V}$ , $0^\circ\text{C} \leq T_A \leq +70^\circ\text{C}$ , $R_L = \infty$
		—	—	3.0		$V_{IN} = 5\text{V}$ , $-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$ , $R_L = \infty$
Negative Charge Pump Output Source Resistance	$R_{OUT}^-$	—	140	180	$\Omega$	$I_L^- = 10\text{ mA}$ , $I_L^+ = 0\text{ mA}$ , $V_{IN} = 5\text{V}$
		—	180	250		$I_L^- = 5\text{ mA}$ , $I_L^+ = 0\text{ mA}$ , $V_{IN} = 2.8\text{V}$
		—	—	220		$0^\circ\text{C} \leq T_A \leq +70^\circ\text{C}$
		—	—	250		$-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$
Positive Charge Pump Output Source Resistance	$R_{OUT}^+$	—	140	180	$\Omega$	$I_L^+ = 10\text{ mA}$ , $I_L^- = 0\text{ mA}$ , $V_{IN} = 5\text{V}$
		—	180	250		$I_L^+ = 5\text{ mA}$ , $I_L^- = 0\text{ mA}$ , $V_{IN} = 2.8\text{V}$
		—	—	220		$0^\circ\text{C} \leq T_A \leq +70^\circ\text{C}$
		—	—	250		$-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$
Oscillator Frequency	$F_{OSC}$	—	21	—	kHz	
Power Efficiency	$P_{EFF}$	—	85	—	%	$R_L = 2\text{ k}\Omega$
Voltage Conversion Efficiency	$V_{OUTEFF}$	97	99	—	%	$V_{OUT}^+$ , $R_L = \infty$
		97	99	—		$V_{OUT}^-$ , $R_L = \infty$

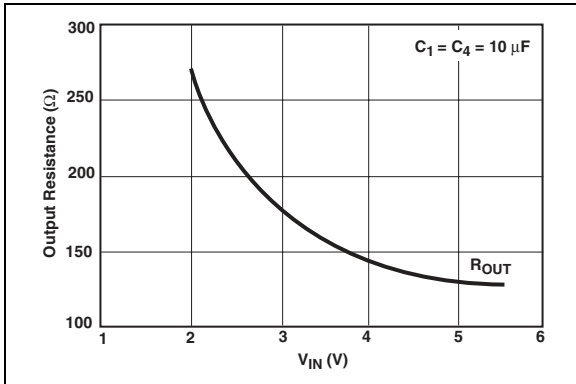


**FIGURE 1-1:** Test Circuit Used For DC Characteristics Table.

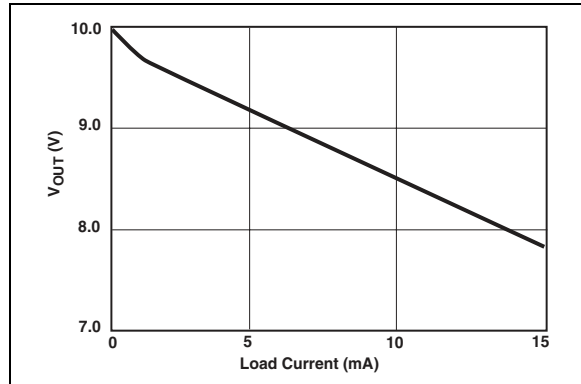
## 2.0 TYPICAL PERFORMANCE CURVES

**Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

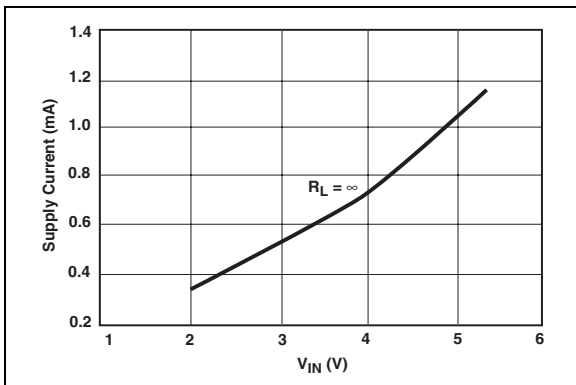
**Note:** Unless otherwise indicated,  $V_{IN} = +5V$ ,  $T_A = +25^\circ C$ .



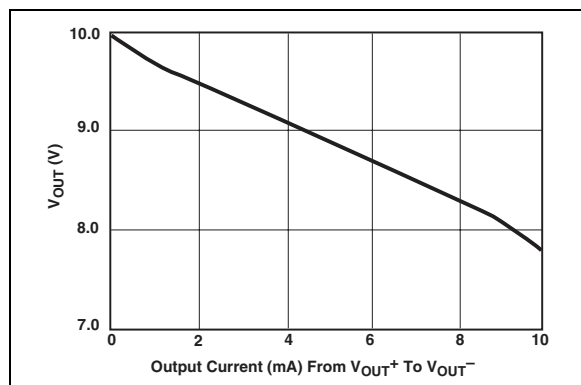
**FIGURE 2-1:** Output Resistance vs.  $V_{IN}$ .



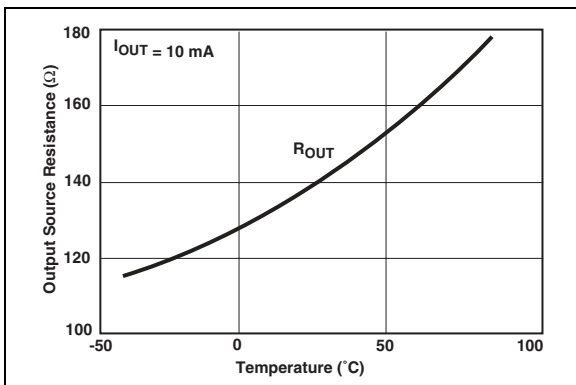
**FIGURE 2-4:**  $V_{OUT}^+$  or  $V_{OUT}^-$  vs. Load Current.



**FIGURE 2-2:** Supply Current vs.  $V_{IN}$ .



**FIGURE 2-5:** Output Voltage vs. Output Current.



**FIGURE 2-3:** Output Source Resistance vs. Temperature.

## 3.0 PIN DESCRIPTION

The descriptions of the pins are listed in Table 3-1.

**TABLE 3-1: PIN FUNCTION TABLE**

Pin No. (8-Pin PDIP, SOIC)	Symbol	Description
1	$C_1^-$	Input. First charge pump capacitor. Negative connection
2	$C_2^+$	Input. Second charge pump capacitor. Positive connection.
3	$C_2^-$	Input. Second charge pump capacitor. Negative connection.
4	$V_{OUT}^-$	Output. Negative Output voltage
5	GND	Input. Ground connection.
6	$V_{IN}$	Input. Power supply.
7	$C_1^+$	Input. First charge pump capacitor. Positive connection.
8	$V_{OUT}^+$	Output. Positive Output Voltage.

### 3.1 First Charge Pump Capacitor ( $C_1^-$ )

Negative connection for the charge pump capacitor (flying capacitor) used to transfer charge from the input source to a second charge pump capacitor. This charge pump capacitor is used to double the input voltage and store the charge in the second charge pump capacitor.

It is recommended that a low ESR (equivalent series resistance) capacitor be used. Additionally, larger values will lower the output resistance.

### 3.2 Second Charge Pump Capacitor ( $C_2^+$ )

Positive connection for the second charge pump capacitor (flying capacitor) used to transfer charge from the first charge pump capacitor to the output.

It is recommended that a low ESR (equivalent series resistance) capacitor be used. Additionally, larger values will lower the output resistance.

### 3.3 Second Charge Pump Capacitor ( $C_2^-$ )

Negative connection for the second charge pump capacitor (flying capacitor) used to transfer charge from the first charge pump capacitor to the output. Proper orientation is imperative when using a polarized capacitor.

### 3.4 Negative Output Voltage ( $V_{OUT}^-$ )

Negative connection for the negative charge pump output capacitor. The negative charge pump output capacitor supplies the output load during the first, third and fourth phases of the switching cycle. During the second phase of the switching cycle, charge is restored to the negative charge pump output capacitor. The negative output voltage magnitude is approximately twice the input voltage.

It is recommended that a low ESR (equivalent series resistance) capacitor be used. Additionally, larger values will lower the output ripple.

### 3.5 Ground (GND)

Input zero volt reference.

### 3.6 Power Supply Input ( $V_{IN}$ )

Positive power supply input voltage connection. It is recommended that a low ESR (equivalent series resistance) capacitor be used to bypass the power supply input to ground (GND).

### 3.7 First Charge Pump Capacitor ( $C_1^+$ )

Positive connection for the charge pump capacitor (flying capacitor) used to transfer charge from the input source to a second charge pump capacitor. Proper orientation is imperative when using a polarized capacitor.

### 3.8 Positive Output Voltage ( $V_{OUT}^+$ )

Positive connection for the positive charge pump output capacitor. The positive charge pump output capacitor supplies the output load during the first, second and third phases of the switching cycle. During the fourth phase of the switching cycle, charge is restored to the positive charge pump output capacitor. The positive output voltage magnitude is approximately twice the input voltage.

It is recommended that a low ESR (equivalent series resistance) capacitor be used. Additionally, larger values will lower the output ripple.

# TCM680

## 4.0 DETAILED DESCRIPTION

### 4.1 $V_{OUT}^-$ Charge Storage - Phase 1

The positive side of capacitors  $C_1$  and  $C_2$  are connected to +5V at the start of this phase.  $C_1^+$  is then switched to ground and the charge in  $C_1^-$  is transferred to  $C_2^-$ . Since  $C_2^+$  is connected to +5V, the voltage potential across capacitor  $C_2$  is now 10V.

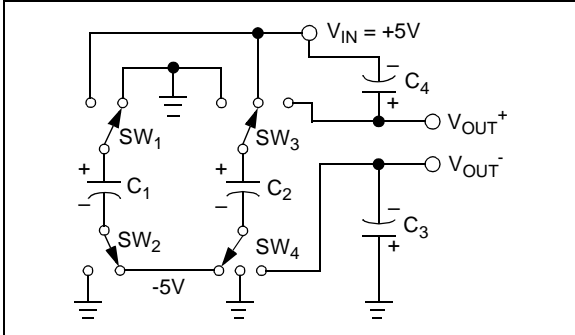


FIGURE 4-1: Charge Pump - Phase 1.

### 4.2 $V_{OUT}^-$ Transfer - Phase 2

Phase two of the clock connects the negative terminal of  $C_2$  to the  $V_{OUT}^-$  storage capacitor  $C_3$  and the positive terminal of  $C_2$  to ground, transferring the generated -10V to  $C_3$ . Simultaneously, the positive side of capacitor  $C_1$  is switched to +5V and the negative side is connected to ground.

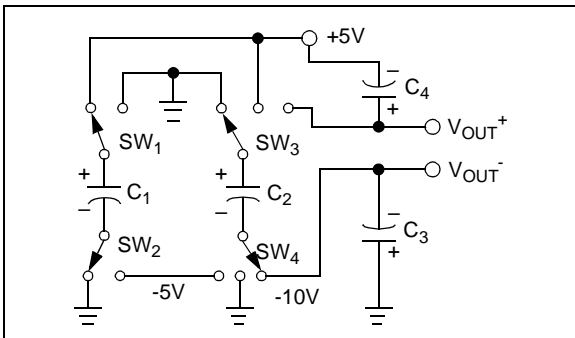


FIGURE 4-2: Charge Pump - Phase 2.

### 4.3 $V_{OUT}^+$ Charge Storage - Phase 3

The third phase of the clock is identical to the first phase – the charge stored in  $C_1$  produces -5V in the negative terminal of  $C_1$ , which is applied to the negative side of capacitor  $C_2$ . Since  $C_2^+$  is at +5V, the voltage potential across  $C_2$  is 10V.

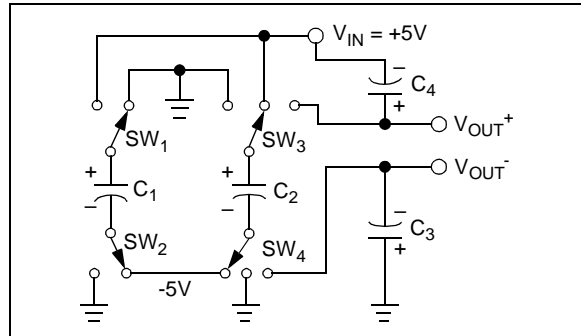


FIGURE 4-3: Charge Pump - Phase 3.

### 4.4 $V_{OUT}^+$ Transfer - Phase 4

The fourth phase of the clock connects the negative terminal of  $C_2$  to ground and transfers the generated 10V across  $C_2$  to  $C_4$ , the  $V_{OUT}^+$  storage capacitor. Simultaneously, the positive side of capacitor  $C_1$  is switched to +5V and the negative side is connected to ground, and the cycle begins again.

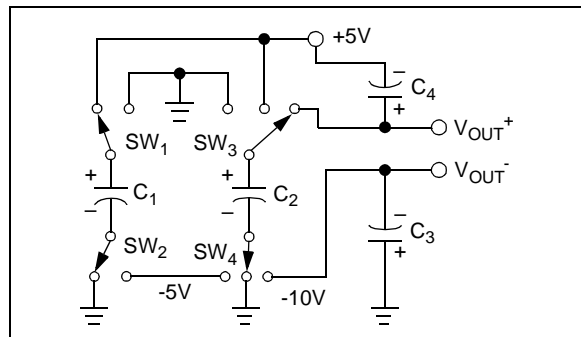


FIGURE 4-4: Charge Pump - Phase 4.

## 4.5 Maximum Operating Limits

The maximum input voltage rating must be observed. The TCM680 will clamp the input voltage to 5.8V. Exceeding this maximum threshold will cause excessive current to flow through the TCM680, potentially causing permanent damage to the device.

## 4.6 Switched Capacitor Converter Power Losses

The overall power loss of a switched capacitor converter is affected by four factors:

1. Losses from power consumed by the internal oscillator, switch drive, etc. These losses will vary with input voltage, temperature and oscillator frequency.
2. Conduction losses in the non-ideal switches.
3. Losses due to the non-ideal nature of the external capacitors.
4. Losses that occur during charge transfer from the pump to reservoir capacitors when a voltage difference between the capacitors exists.

The power loss for the TCM680 is calculated using the following equation:

### EQUATION

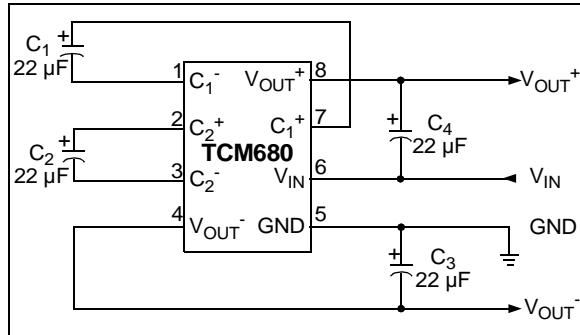
$$P_{LOSS} = (I_{OUT+})^2 \times R_{OUT-} + (I_{OUT-})^2 \times R_{OUT+} + I_{IN} \times V_{IN}$$

# TCM680

## 5.0 APPLICATIONS INFORMATION

### 5.1 Voltage Multiplication and Inversion

The TCM680 performs voltage multiplication and inversion simultaneously, providing positive and negative outputs (Figure 5-1). The magnitude of both outputs is, approximately, twice the input voltage. Unlike other switched capacitor converters, the TCM680 requires only four external capacitors to provide both functions simultaneously.



**FIGURE 5-1:** Positive and Negative Converter.

### 5.2 Capacitor Selection

The TCM680 requires only 4 external capacitors for operation, which can be inexpensive, polarized aluminum electrolytic types. For the circuit in Figure 5-1, the output characteristics are largely determined by the external capacitors. An expression for  $R_{OUT}$  can be derived as shown below:

#### EQUATION

$$R_{OUT}^{+} = 4(R_{SW1} + R_{SW2} + ESR_{C1} + R_{SW3} + R_{SW4} + ESR_{C2}) + 4(R_{SW1} + R_{SW2} + ESR_{C1} + R_{SW3} + R_{SW4} + ESR_{C2}) + 1/(f_{PUMP} \times C1) + 1/(f_{PUMP} \times C2) + ESR_{C4}$$

$$R_{OUT}^{-} = 4(R_{SW1} + R_{SW2} + ESR_{C1} + R_{SW3} + R_{SW4} + ESR_{C2}) + 4(R_{SW1} + R_{SW2} + ESR_{C1} + R_{SW3} + R_{SW4} + ESR_{C2}) + 1/(f_{PUMP} \times C1) + 1/(f_{PUMP} \times C2) + ESR_{C3}$$

Assuming all switch resistances are approximately equal:

#### EQUATION

$$R_{OUT}^{+} = 32R_{SW} + 8ESR_{C1} + 8ESR_{C2} + ESR_{C4} + 1/(f_{PUMP} \times C1) + 1/(f_{PUMP} \times C2)$$

$$R_{OUT}^{-} = 32R_{SW} + 8ESR_{C1} + 8ESR_{C2} + ESR_{C3} + 1/(f_{PUMP} \times C1) + 1/(f_{PUMP} \times C2)$$

$R_{OUT}$  is typically  $140\Omega$  at  $+25^{\circ}\text{C}$  with  $V_{IN} = +5\text{V}$  and  $C_1$  and  $C_2$  as  $4.7\ \mu\text{F}$  low ESR capacitors. The fixed term ( $32R_{SW}$ ) is about  $130\Omega$ . It can easily be seen that increasing or decreasing values of  $C_1$  and  $C_2$  will affect efficiency by changing  $R_{OUT}$ . However, be careful about ESR. This term can quickly become dominant with large electrolytic capacitors. Table 5-1 shows  $R_{OUT}$  for various values of  $C_1$  and  $C_2$  (assume  $0.5\Omega$  ESR).  $C_1$  and  $C_4$  must be rated at 6 VDC or greater while  $C_2$  and  $C_3$  must be rated at 12 VDC or greater.

Output voltage ripple is affected by  $C_3$  and  $C_4$ . Typically, the larger the value of  $C_3$  and  $C_4$ , the less the ripple for a given load current. The formula for  $V_{RIPPLE(p-p)}$  is given below:

#### EQUATION

$$V_{RIPPLE(p-p)}^{+} = \{1/[2(f_{PUMP}/3) \times C4] + 2(ESR_{C4})\} (I_{OUT}^{+})$$

$$V_{RIPPLE(p-p)}^{-} = \{1/[2(f_{PUMP}/3) \times C3] + 2(ESR_{C3})\} (I_{OUT}^{-})$$

For a  $10\ \mu\text{F}$  ( $0.5\Omega$  ESR) capacitor for  $C_3$ ,  $C_4$ ,  $f_{PUMP} = 21\ \text{kHz}$  and  $I_{OUT} = 10\ \text{mA}$ , the peak-to-peak ripple voltage at the output will be less than  $100\ \text{mV}$ . In most applications ( $I_{OUT} \leq 10\ \text{mA}$ ),  $10\text{-}20\ \mu\text{F}$  output capacitors and  $1\text{-}5\ \mu\text{F}$  pump capacitors will suffice. Table 5-2 shows  $V_{RIPPLE}$  for different values of  $C_3$  and  $C_4$  (assume  $1\ \Omega$  ESR).

**TABLE 5-1: OUTPUT RESISTANCE VS.  $C_1, C_2$**

$C_1, C_2$ ( $\mu\text{F}$ )	$R_{OUT}^{+}, R_{OUT}^{-}$ ( $\Omega$ )
0.1	1089
0.47	339
1	232
3.3	165
4.7	157
10	146
22	141
100	137

**TABLE 5-2:  $V_{RIPPLE}$  PEAK-TO-PEAK VS.  $C_3, C_4$  ( $I_{OUT} 10\ \text{mA}$ )**

$C_3, C_4$ ( $\mu\text{F}$ )	$V_{RIPPLE(p-p)}^{+}, V_{RIPPLE(p-p)}^{-}$ (mV)
0.47	1540
1	734
3.3	236
4.7	172
10	91
22	52
100	27



## 5.3 Paralleling Devices

To reduce the value of  $R_{OUT^-}$  and  $R_{OUT^+}$ , multiple TCM680 voltage converters can be connected in parallel (Figure 5-2). The output resistance of both outputs will be reduced, approximately, by a factor of n, where n is the number of devices connected in parallel.

### EQUATION

$$R_{OUT^-} = \frac{R_{OUT^-} \text{ (of TCM680)}}{n \text{ (number of devices)}}$$

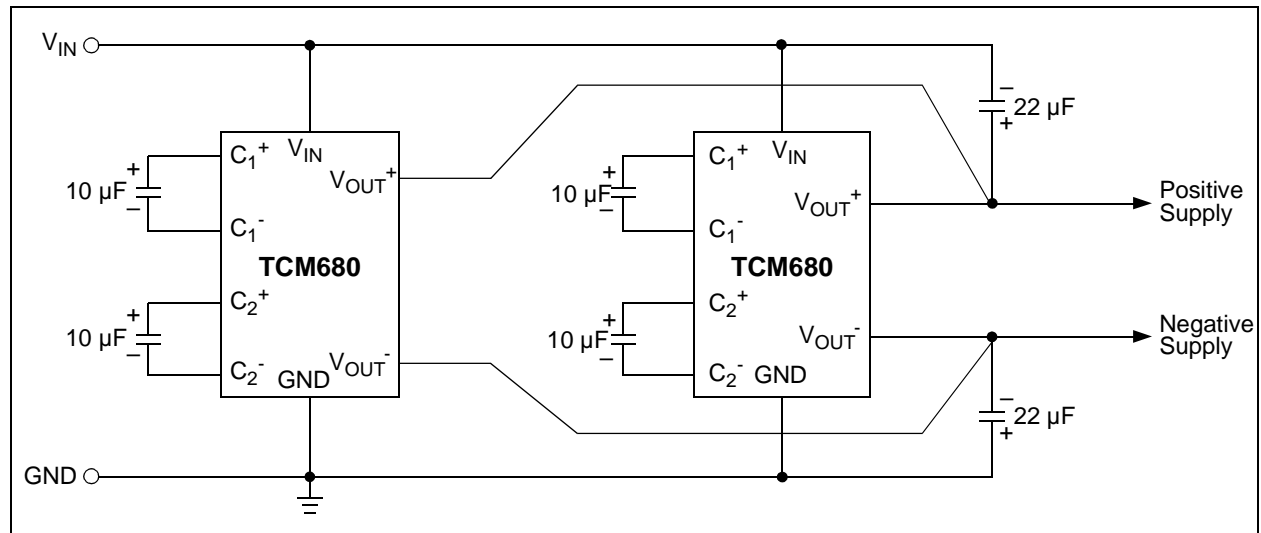
### EQUATION

$$R_{OUT^+} = \frac{R_{OUT^+} \text{ (of TCM680)}}{n \text{ (number of devices)}}$$

Each device requires its own pump capacitors, but all devices may share the same reservoir capacitors. To preserve ripple performance, the value of the reservoir capacitors should be scaled according to the number of devices connected in parallel.

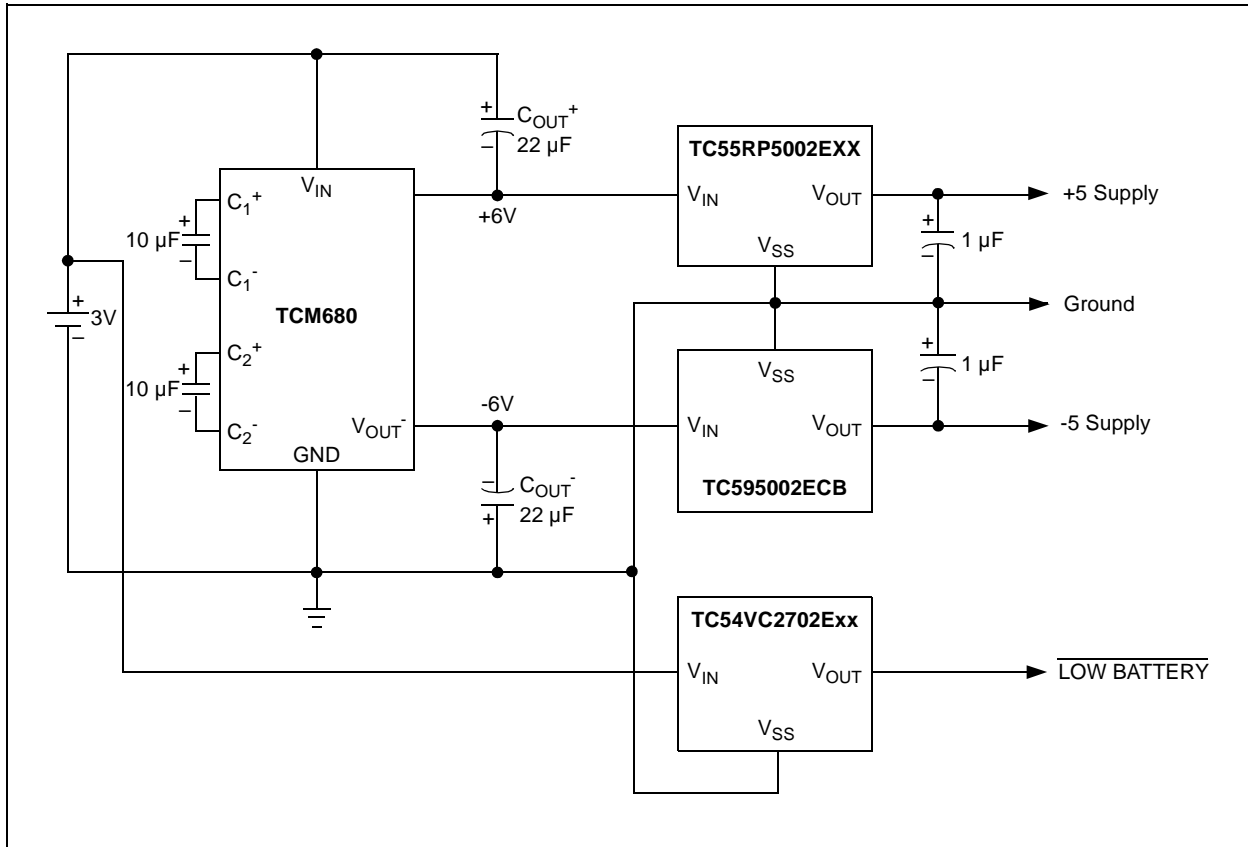
## 5.4 Output Voltage Regulation

The outputs of the TCM680 can be regulated to provide +5V from a 3V input source (Figure 5-3). The TCM680 performs voltage multiplication and inversion producing output voltages of, approximately, +6V. The TCM680 outputs are regulated to +5V with the linear regulators TC55 and TC59. The TC54 is a voltage detector providing an indication that the input source is low and that the outputs may fall out of regulation. The input source to the TCM680 can vary from 2.8V to 5.5V without adversely affecting the output regulation making this application well suited for use with single cell Li-Ion batteries or three alkaline or nickel based batteries connected in series.



**FIGURE 5-2:** Paralleling TCM680 for Lower Output Source Resistance.

# TCM680

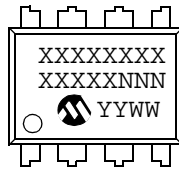


**FIGURE 5-3:** Split Supply Derived from 3V Battery.

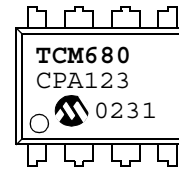
## 6.0 PACKAGING INFORMATION

### 6.1 Packaging Marking Information

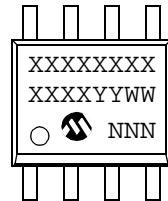
8-Lead PDIP (300 mil)



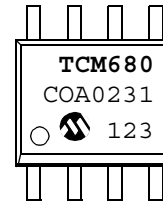
Example:



8-Lead SOIC (150 mil)



Example:

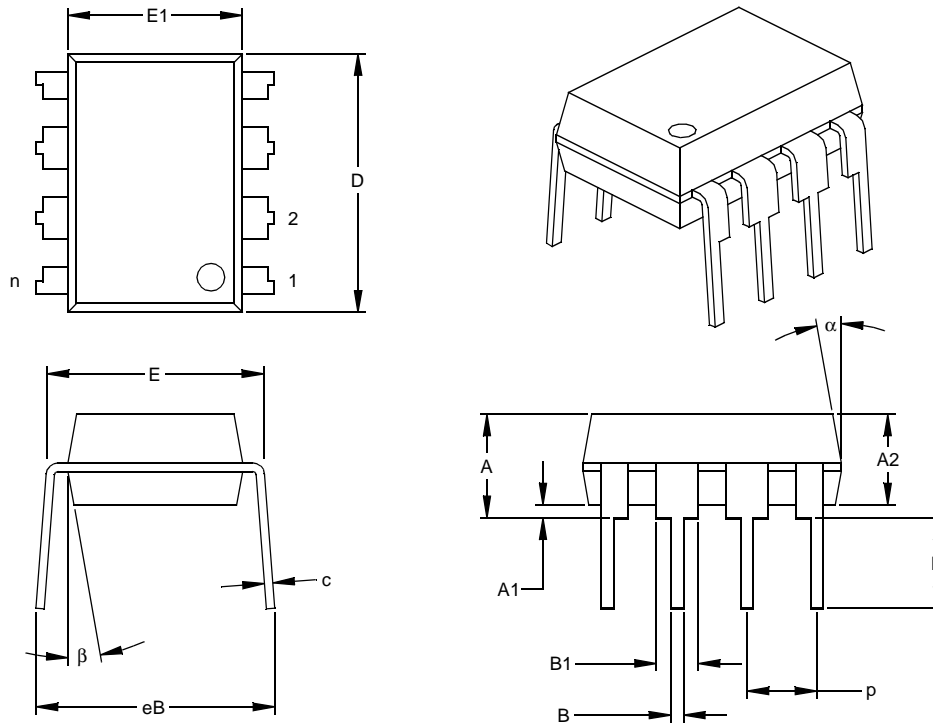


<b>Legend:</b>	XX...X	Customer specific information*
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
<b>Note:</b>	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.	

\* Standard OTP marking consists of Microchip part number, year code, week code, and traceability code.

# TCM680

## 8-Lead Plastic Dual In-line (P) – 300 mil (PDIP)



Dimension Limits	Units	INCHES*			MILLIMETERS		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§ eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

\* Controlling Parameter

§ Significant Characteristic

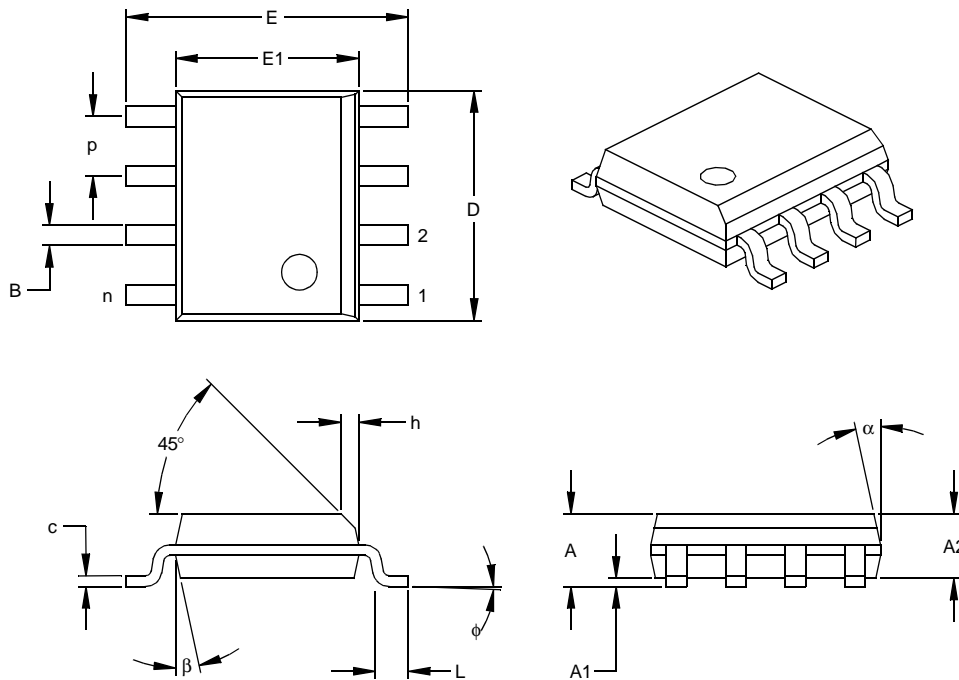
Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-001

Drawing No. C04-018

## 8-Lead Plastic Small Outline (SN) – Narrow, 150 mil (SOIC)



Units		INCHES*			MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.050			1.27	
Overall Height	A	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff §	A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	E	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	L	.019	.025	.030	0.48	0.62	0.76
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.008	.009	.010	0.20	0.23	0.25
Lead Width	B	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

\* Controlling Parameter  
 § Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-012

Drawing No. C04-057

# TCM680

---

NOTES:

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>		<u>X</u>	<u>/XX</u>
Device	Temperature Range		Package
Device:	TCM680:		Charge Pump Converter
Temperature Range:	C	=	0°C to +70°C
	E	=	-40°C to +85°C
Package:	PA	=	Plastic DIP (300 mil Body), 8-lead
	OA	=	Plastic SOIC, (150 mil Body), 8-lead
	OATR	=	Plastic SOIC, (150 mil Body), 8-lead (Tape and Reel)

**Examples:**

- a) TCM680COA: Charge Pump Converter, SOIC pkg, 0°C to +70°C.
- b) TCM680COATR: Charge Pump Converter, SOIC pkg, 0°C to +70°C, Tape and Reel.
- c) TCM680CPA: Charge Pump Converter, PDIP pkg, 0°C to +70°C.
- d) TCM680EOA: Charge Pump Converter, SOIC pkg, -40°C to +85°C.
- e) TCM680EOATR: Charge Pump Converter, SOIC pkg, -40°C to +85°C, Tape and Reel.
- f) TCM680EPA: Charge Pump Converter, PDIP pkg, -40°C to +85°C.

## Sales and Support

### Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Corporate Literature Center U.S. FAX: (480) 792-7277
3. The Microchip Worldwide Site ([www.microchip.com](http://www.microchip.com))

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

### New Customer Notification System

Register on our web site ([www.microchip.com/cn](http://www.microchip.com/cn)) to receive the most current information on our products.

# TCM680

---

NOTES:



---

---

**Note the following details of the code protection feature on Microchip devices:**

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

---

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip's products as critical components in life support systems is not authorized except with express written approval by Microchip. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

**Trademarks**

The Microchip name and logo, the Microchip logo, Accuron, dsPIC, KEELoQ, microID, MPLAB, PIC, PICmicro, PICSTART, PRO MATE, PowerSmart, rPIC, and SmartShunt are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

AmpLab, FilterLab, Migratable Memory, MXDEV, MXLAB, PICMASTER, SEEVAL, SmartSensor and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, Application Maestro, dsPICDEM, dsPICDEM.net, dsPICworks, ECAN, ECONOMONITOR, FanSense, FlexROM, fuzzyLAB, In-Circuit Serial Programming, ICSP, ICEPIC, Linear Active Thermistor, MPASM, MPLIB, MPLINK, MPSIM, PCKIT, PICDEM, PICDEM.net, PICLAB, PICtail, PowerCal, PowerInfo, PowerMate, PowerTool, rLAB, rPICDEM, Select Mode, Smart Serial, SmartTel, Total Endurance and WiperLock are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2005, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

 Printed on recycled paper.

**QUALITY MANAGEMENT SYSTEM**  
**CERTIFIED BY DNV**  
**== ISO/TS 16949:2002 ==**

*Microchip received ISO/TS-16949:2002 quality system certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona and Mountain View, California in October 2003. The Company's quality system processes and procedures are for its PICmicro® 8-bit MCUs, KEELoQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.*



---

---

## WORLDWIDE SALES AND SERVICE

---

---

### AMERICAS

**Corporate Office**  
2355 West Chandler Blvd.  
Chandler, AZ 85224-6199  
Tel: 480-792-7200  
Fax: 480-792-7277  
Technical Support:  
<http://support.microchip.com>  
Web Address:  
[www.microchip.com](http://www.microchip.com)

**Atlanta**  
Alpharetta, GA  
Tel: 770-640-0034  
Fax: 770-640-0307

**Boston**  
Westborough, MA  
Tel: 774-760-0087  
Fax: 774-760-0088

**Chicago**  
Itasca, IL  
Tel: 630-285-0071  
Fax: 630-285-0075

**Dallas**  
Addison, TX  
Tel: 972-818-7423  
Fax: 972-818-2924

**Detroit**  
Farmington Hills, MI  
Tel: 248-538-2250  
Fax: 248-538-2260

**Kokomo**  
Kokomo, IN  
Tel: 765-864-8360  
Fax: 765-864-8387

**Los Angeles**  
Mission Viejo, CA  
Tel: 949-462-9523  
Fax: 949-462-9608

**San Jose**  
Mountain View, CA  
Tel: 650-215-1444  
Fax: 650-961-0286

**Toronto**  
Mississauga, Ontario,  
Canada  
Tel: 905-673-0699  
Fax: 905-673-6509

### ASIA/PACIFIC

**Australia - Sydney**  
Tel: 61-2-9868-6733  
Fax: 61-2-9868-6755

**China - Beijing**  
Tel: 86-10-8528-2100  
Fax: 86-10-8528-2104

**China - Chengdu**  
Tel: 86-28-8676-6200  
Fax: 86-28-8676-6599

**China - Fuzhou**  
Tel: 86-591-8750-3506  
Fax: 86-591-8750-3521

**China - Hong Kong SAR**  
Tel: 852-2401-1200  
Fax: 852-2401-3431

**China - Qingdao**  
Tel: 86-532-8502-7355  
Fax: 86-532-8502-7205

**China - Shanghai**  
Tel: 86-21-5407-5533  
Fax: 86-21-5407-5066

**China - Shenyang**  
Tel: 86-24-2334-2829  
Fax: 86-24-2334-2393

**China - Shenzhen**  
Tel: 86-755-8203-2660  
Fax: 86-755-8203-1760

**China - Shunde**  
Tel: 86-757-2839-5507  
Fax: 86-757-2839-5571

**China - Wuhan**  
Tel: 86-27-5980-5300  
Fax: 86-27-5980-5118

**China - Xian**  
Tel: 86-29-8833-7250  
Fax: 86-29-8833-7256

### ASIA/PACIFIC

**India - Bangalore**  
Tel: 91-80-2229-0061  
Fax: 91-80-2229-0062

**India - New Delhi**  
Tel: 91-11-5160-8631  
Fax: 91-11-5160-8632

**India - Pune**  
Tel: 91-20-2566-1512  
Fax: 91-20-2566-1513

**Japan - Yokohama**  
Tel: 81-45-471-6166  
Fax: 81-45-471-6122

**Korea - Gumi**  
Tel: 82-54-473-4301  
Fax: 82-54-473-4302

**Korea - Seoul**  
Tel: 82-2-554-7200  
Fax: 82-2-558-5932 or  
82-2-558-5934

**Malaysia - Penang**  
Tel: 60-4-646-8870  
Fax: 60-4-646-5086

**Philippines - Manila**  
Tel: 63-2-634-9065  
Fax: 63-2-634-9069

**Singapore**  
Tel: 65-6334-8870  
Fax: 65-6334-8850

**Taiwan - Hsin Chu**  
Tel: 886-3-572-9526  
Fax: 886-3-572-6459

**Taiwan - Kaohsiung**  
Tel: 886-7-536-4818  
Fax: 886-7-536-4803

**Taiwan - Taipei**  
Tel: 886-2-2500-6610  
Fax: 886-2-2508-0102

**Thailand - Bangkok**  
Tel: 66-2-694-1351  
Fax: 66-2-694-1350

### EUROPE

**Austria - Wels**  
Tel: 43-7242-2244-399  
Fax: 43-7242-2244-393

**Denmark - Copenhagen**  
Tel: 45-4450-2828  
Fax: 45-4485-2829

**France - Paris**  
Tel: 33-1-69-53-63-20  
Fax: 33-1-69-30-90-79

**Germany - Munich**  
Tel: 49-89-627-144-0  
Fax: 49-89-627-144-44

**Italy - Milan**  
Tel: 39-0331-742611  
Fax: 39-0331-466781

**Netherlands - Drunen**  
Tel: 31-416-690399  
Fax: 31-416-690340

**Spain - Madrid**  
Tel: 34-91-708-08-90  
Fax: 34-91-708-08-91

**UK - Wokingham**  
Tel: 44-118-921-5869  
Fax: 44-118-921-5820